



Initial Application Deadline	May 31(Wed.), 2006
Received dated	

Jisso Process Technology Exhibition 2006

We bear full knowledge of the Exhibition Regulation of Jisso Process Technology Exhibition 2006 and herewith apply to exhibit as given below.

Booth Type	Number of Booths
M Type	_____Booth(s)
S Type	_____Booth(s)

We will accept only one booth and two booths for S Type.

Booth Format Request

4, 5, 6, 8, 12, 14, 16 booths	Please choose _____A _____B
Block booth (over 20 booths)	Please specify a booth size _____m(W) × _____m(D)

Please tick one

<input type="checkbox"/> Regular Member of Japan Robot Association
<input type="checkbox"/> Supporting Member (corporation) of Japan Robot Association
<input type="checkbox"/> Member of Japan Electronics Show Association
<input type="checkbox"/> Member of Association Connecting Electronics Industries who exhibited at APEX 2006
<input type="checkbox"/> Non Member

Items to be Exhibited

Made in Japan _____%	Foreign made _____% (Name of Country _____)
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Main items to be exhibited (In case items are foreign made or from more than 2 companies, please indicate the model name, company name and country name.)

Please specify the percentage of the items to be exhibited in your booth.

Electronic components mounting machines and related equipment/systems _____%	Electronic manufacturing device packaging materials _____%
PCB Assembly related equipment and systems _____%	Electronic packaging joint systems _____%
Semiconductor mounting equipment and systems _____%	High frequency responding devices, components, and materials _____%
Inspection and testing equipment _____%	Environment related equipment and components and materials _____%
Electronic packaging design systems _____%	Publications _____%
Electronic packaging devices, components and related materials _____%	Others _____%

Joint Participation	<input type="checkbox"/> Yes (Name of Company _____)	<input type="checkbox"/> No
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For JESA use only :

Person in charge	
Date Entry	
Invoice Issued	
Booth No.	

Company Details

Company Name	
Address of head office	
President	Position
Contact	Division
Address	
Telephone	FAX
E-mail	

Agent and/or Representative in Japan

Name of Company	
Contact	E-mail
Telephone	FAX

Signed by : _____ Date : _____
(Notes)

- Please submit this Form after filling in the information sheet regarding "Handling Items of Electronic Manufacturing Process". (See the reverse side.)
- In case any amendments are necessary, please inform the Secretariat in writing in order to receive approval.



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Handling Items of Electronic Manufacturing Process

Please tick your company's Item(s) Handled.

Electronic Components Mounting Machines and Related Equipment/Systems

- Electronic Component Placement Machine
- Electronic Component Insertion Machine
- Solderpaste Printing Machine
- Flow Soldering Equipment
 - Dip Cask
 - Reflow Oven
- Dispenser
- Other _____

PCB Assembly and Related Equipment/Systems

- (PCB) Transfer System
- Substrate Manufacturing Equipment and System
- Taping Machine and Material
- Bulk Feeder
- Other Feeder
- Automatic Assembly Equipment
- Other _____

Semiconductor Mounting Equipment/Systems

- Wire Bonding Machine
- Die Bonding Machine
- Flip Chip Electronic Manufacturing System
- LCD/COG Bonding System
- BGA/CSP Assembling System
- TAB Mounting System
- OLB/ILB System
- COB System
- Other _____

Inspection and Testing Equipment

- Testing Equipment for the External Appearance of the Substrate
- Testing and Measuring Equipment for Semiconductor Manufacturing
- Testing and Measuring Equipment for Other Mounting Machine
- Other _____

Electronic Packaging Design Systems

- Designing Tool
- Production Optimization Software
- Electronic Packaging Programming Equipment
- Printed Circuit Board
- Other _____

Electronic Packaging Devices, Components and Related Materials

- SMD
- MCM/LSI Package
- Circuit Molding Material and Device
 - Chip Component
 - IC/QFP
 - Connector and Socket
 - Switch
 - Sealing Resin
 - Adhesive
- Bulk Supply Component
- Other _____

Electronic Manufacturing Device Packaging Materials

- Taping Reel
- Carrier Tape
- TAB Tape/Reel
- Magazine Stick
- IC Tray
- Bulk Case
- Other _____

Electronic Packaging Joint Systems

- System
- Flow Soldering Equipment
- Solder/Joint Material
- Underfill Material
- Other _____

High Frequency Responding Devices, Components, and Materials

- Equipment
- Component
- Material
- Other _____

Environment Related Equipment and Components and Materials

- Zero Mission Process
- Waste Matter Collection and Processing Related Equipment
- Waste Matter Collection and Processing Related Material
- Other _____

Publications

- _____
- _____

Others

- _____
- _____
- _____

Name of Exhibitor		
Contact	Sect./Dept.	
	Name	